

## 30V N-Channel NexFET™ Power MOSFET

Check for Samples: [CSD17303Q5](#)

### FEATURES

- Optimized for 5V Gate Drive
- Ultralow  $Q_g$  and  $Q_{gd}$
- Low Thermal Resistance
- Avalanche Rated
- Pb Free Terminal Plating
- RoHS Compliant
- Halogen Free
- SON 5-mm × 6-mm Plastic Package

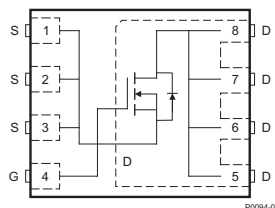
### APPLICATIONS

- Notebook Point-of-Load
- Point-of-Load Synchronous Buck in Networking, Telecom and Computing Systems
- Optimized for Synchronous FET Applications

### DESCRIPTION

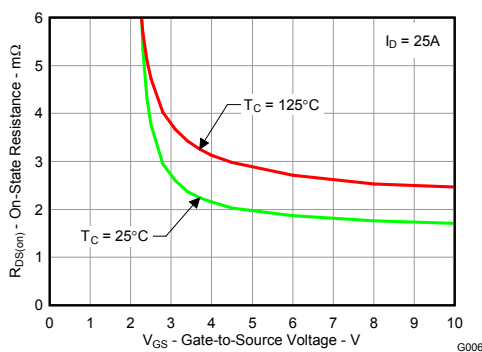
The NexFET™ power MOSFET has been designed to minimize losses in power conversion applications, and optimized for 5V gate drive applications.

Top View



P0094-01

$R_{DS(on)}$  vs  $V_{GS}$



### PRODUCT SUMMARY

$V_{DS}$	Drain to Source Voltage	30	V
$Q_g$	Gate Charge Total (4.5V)	18	nC
$Q_{gd}$	Gate Charge Gate to Drain	4	nC
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 3V$	2.7 mΩ
		$V_{GS} = 4.5V$	2 mΩ
		$V_{GS} = 8V$	1.7 mΩ
$V_{GS(th)}$	Threshold Voltage	1.1	V

### ORDERING INFORMATION

Device	Package	Media	Qty	Ship
CSD17303Q5	SON 5-mm × 6-mm Plastic Package	13-Inch Reel	2500	Tape and Reel

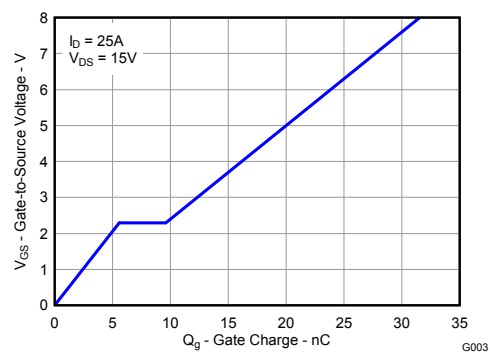
### ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$ unless otherwise stated		VALUE	UNIT
$V_{DS}$	Drain to Source Voltage	30	V
$V_{GS}$	Gate to Source Voltage	+10 / -8	V
$I_D$	Continuous Drain Current, $T_C = 25^\circ\text{C}$	100	A
	Continuous Drain Current <sup>(1)</sup>	32	A
$I_{DM}$	Pulsed Drain Current, $T_A = 25^\circ\text{C}$ <sup>(2)</sup>	200	A
$P_D$	Power Dissipation <sup>(1)</sup>	3.2	W
$T_J$ , $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$E_{AS}$	Avalanche Energy, single pulse $I_D = 103A$ , $L = 0.1mH$ , $R_G = 25\Omega$	530	mJ

(1)  $R_{\theta JA} = 39^\circ\text{C/W}$  on 1-inch<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz. (0.071-mm thick) Cu pad on a 0.06-inch (1.52-mm) thick FR4 PCB.

(2) Pulse duration  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$

GATE CHARGE



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## ELECTRICAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

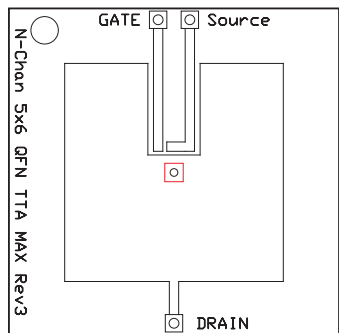
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Static Characteristics						
BV <sub>DSS</sub>	Drain to Source Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30			V
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 24V	1			μA
I <sub>GSS</sub>	Gate to Source Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = +10/−8V	100			nA
V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.9	1.1	1.6	V
R <sub>DS(on)</sub>	Drain to Source On Resistance	V <sub>GS</sub> = 3V, I <sub>D</sub> = 25A	2.7		3.7	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 25A	2		2.6	mΩ
		V <sub>GS</sub> = 8V, I <sub>D</sub> = 25A	1.7		2.4	mΩ
g <sub>fs</sub>	Transconductance	V <sub>DS</sub> = 15V, I <sub>D</sub> = 25A	114			S
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 15V, f = 1MHz	2630	3420	pF	
C <sub>oss</sub>	Output Capacitance		1440	1870	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance		83	108	pF	
R <sub>G</sub>	Series Gate Resistance		1.4	2.8	Ω	
Q <sub>g</sub>	Gate Charge Total (4.5V)	V <sub>DS</sub> = 15V, I <sub>DS</sub> = 25A	18	23	nC	
Q <sub>gd</sub>	Gate Charge Gate to Drain		4	nC		
Q <sub>gs</sub>	Gate Charge Gate to Source		5.6	nC		
Q <sub>g(th)</sub>	Gate Charge at V <sub>th</sub>		3	nC		
Q <sub>oss</sub>	Output Charge	V <sub>DS</sub> = 13.7V, V <sub>GS</sub> = 0V	34	nC		
t <sub>d(on)</sub>	Turn On Delay Time	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 4.5V, I <sub>DS</sub> = 25A, R <sub>G</sub> = 2Ω	11.4	ns		
t <sub>r</sub>	Rise Time		16	ns		
t <sub>d(off)</sub>	Turn Off Delay Time		27	ns		
t <sub>f</sub>	Fall Time		10.4	ns		
Diode Characteristics						
V <sub>SD</sub>	Diode Forward Voltage	I <sub>SD</sub> = 25A, V <sub>GS</sub> = 0V	0.8	1	V	
Q <sub>rr</sub>	Reverse Recovery Charge	V <sub>DD</sub> = 13.7V, I <sub>F</sub> = 25A, di/dt = 300A/μs	50	nC		
t <sub>rr</sub>	Reverse Recovery Time		33	ns		

## THERMAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

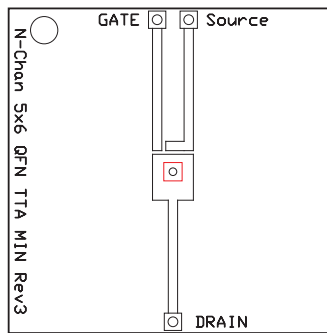
PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Thermal Resistance Junction to Case <sup>(1)</sup>			1.1	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient <sup>(1)(2)</sup>			49	$^\circ\text{C/W}$

- (1)  $R_{\theta JC}$  is determined with the device mounted on a 1-inch<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz. (0.071-mm thick) Cu pad on a 1.5-inch  $\times$  1.5-inch (3.81-cm  $\times$  3.81-cm), 0.06-inch (1.52-mm) thick FR4 PCB.  $R_{\theta JC}$  is specified by design, whereas  $R_{\theta JA}$  is determined by the user's board design.
- (2) Device mounted on FR4 material with 1-inch<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz. (0.071-mm thick) Cu.



M0137-01

Max  $R_{\theta JA} = 49^{\circ}\text{C/W}$   
when mounted on  
1 inch<sup>2</sup> (6.45 cm<sup>2</sup>) of  
2-oz. (0.071-mm thick)  
Cu.

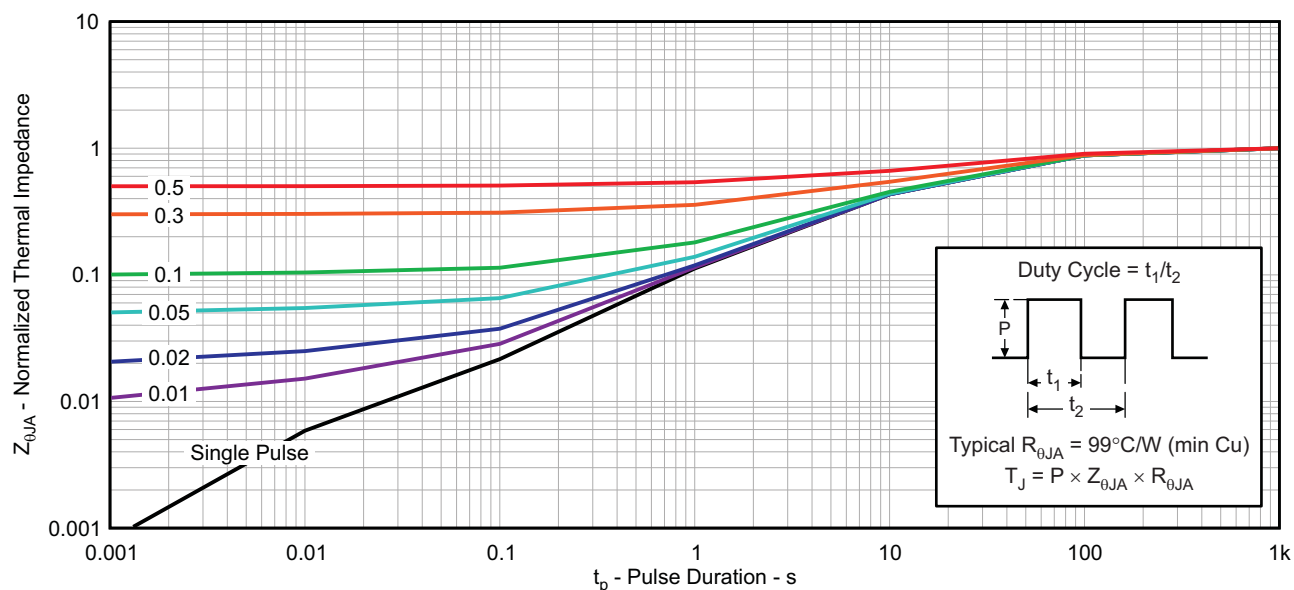


M0137-02

Max  $R_{\theta JA} = 124^{\circ}\text{C/W}$   
when mounted on  
minimum pad area of  
2-oz. (0.071-mm thick)  
Cu.

## TYPICAL MOSFET CHARACTERISTICS

$T_A = 25^{\circ}\text{C}$ , unless otherwise specified



G012

Figure 1. Transient Thermal Impedance

## TYPICAL MOSFET CHARACTERISTICS (continued)

$T_A = 25^\circ\text{C}$ , unless otherwise specified

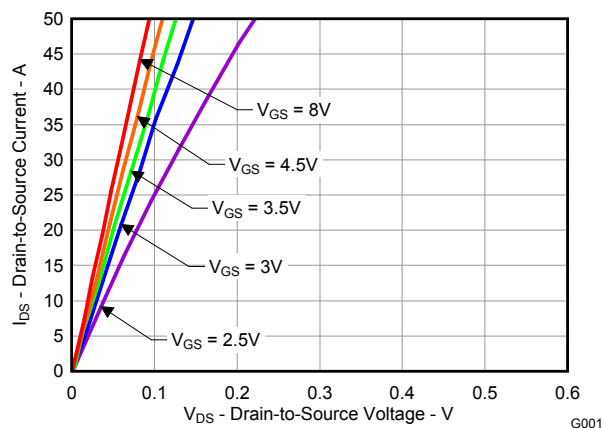


Figure 2. Saturation Characteristics

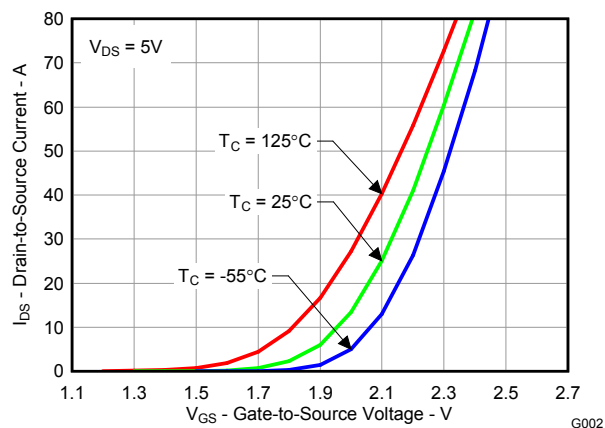


Figure 3. Transfer Characteristics

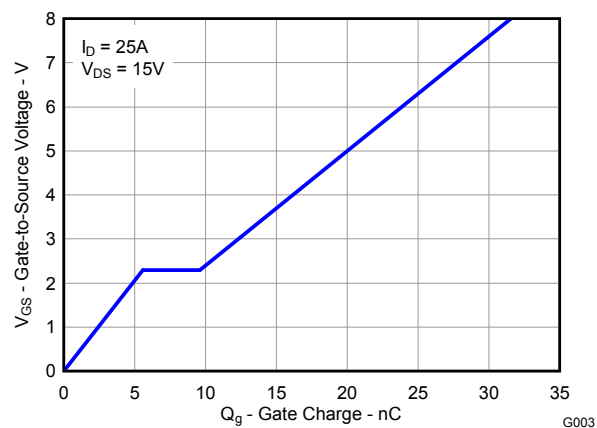


Figure 4. Gate Charge

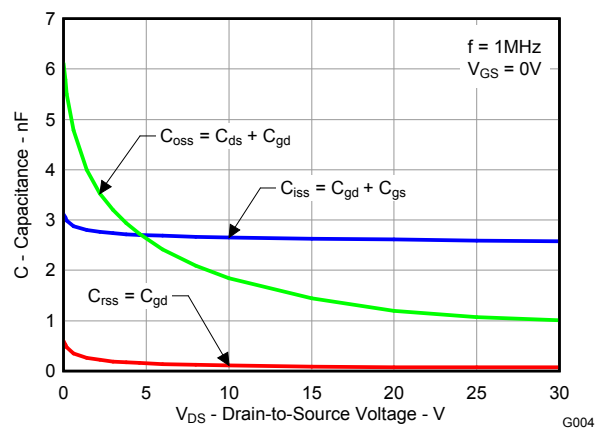


Figure 5. Capacitance

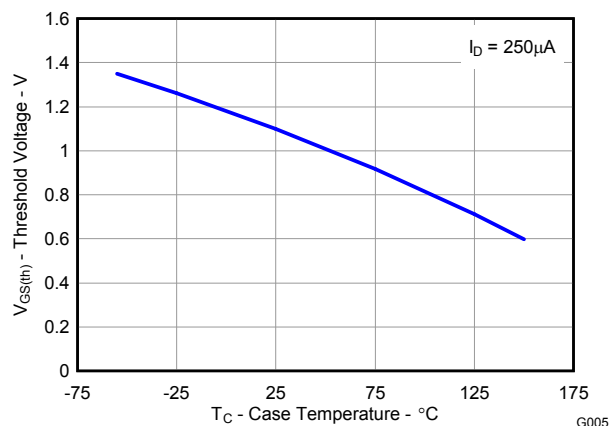


Figure 6. Threshold Voltage vs. Temperature

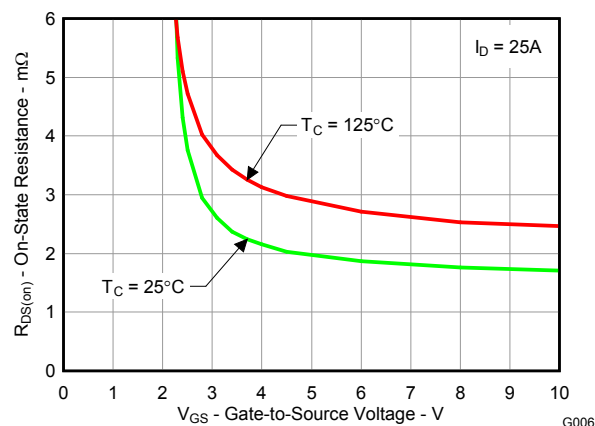


Figure 7. On-State Resistance vs. Gate-to-Source Voltage

## TYPICAL MOSFET CHARACTERISTICS (continued)

$T_A = 25^\circ\text{C}$ , unless otherwise specified

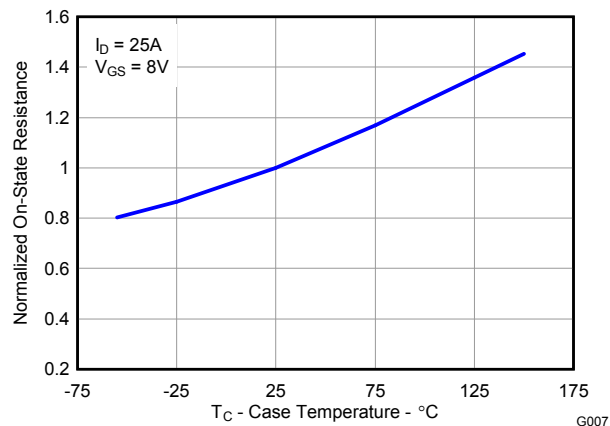


Figure 8. Normalized On-State Resistance vs. Temperature

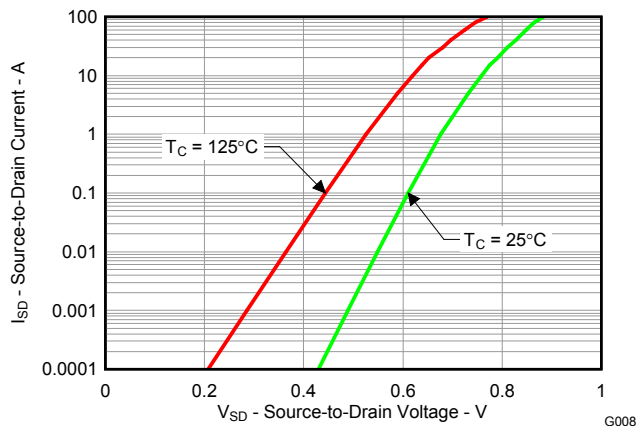


Figure 9. Typical Diode Forward Voltage

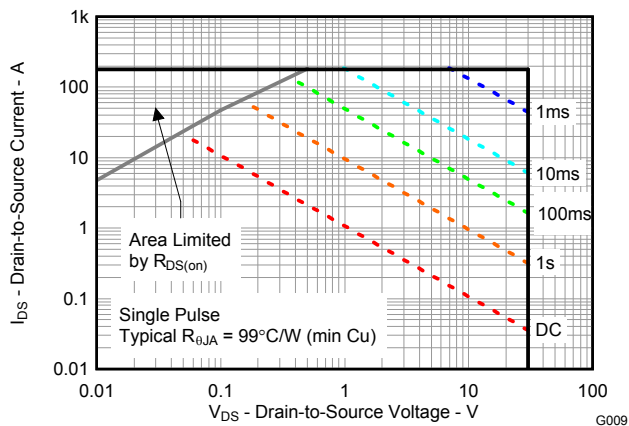


Figure 10. Maximum Safe Operating Area

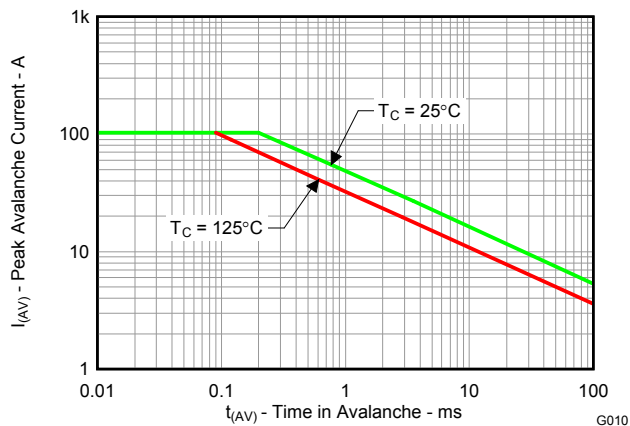


Figure 11. Single Pulse Unclamped Inductive Switching

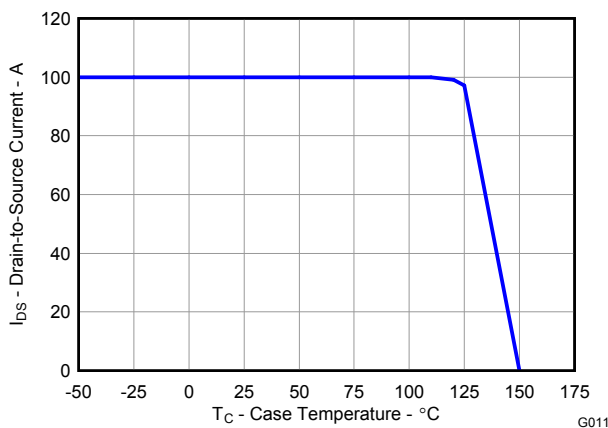
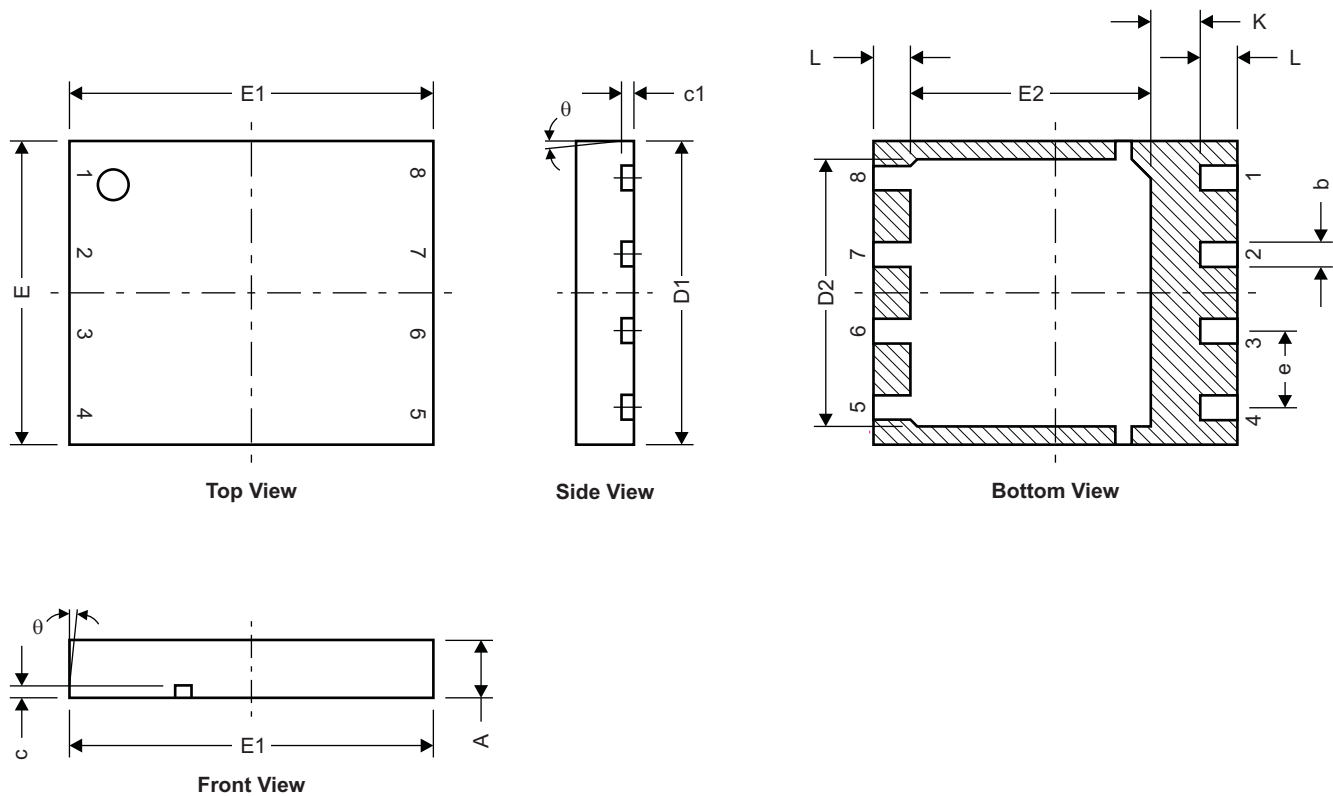


Figure 12. Maximum Drain Current vs. Temperature

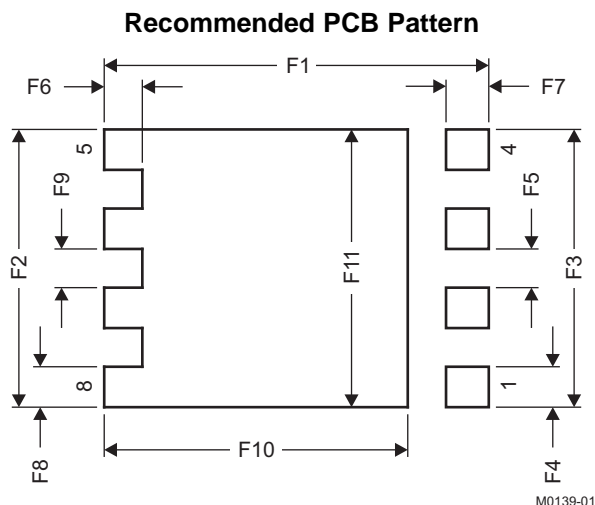
## MECHANICAL DATA

### Q5 Package Dimensions



M0140-01

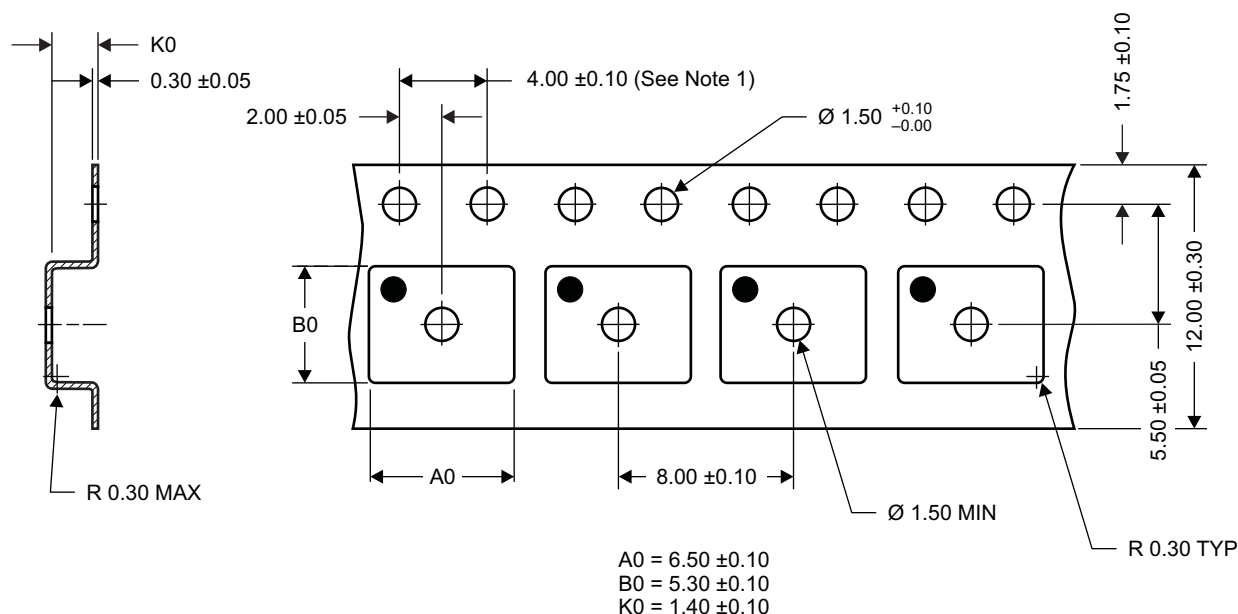
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.950	1.050	0.037	0.039
b	0.360	0.460	0.014	0.018
c	0.150	0.250	0.006	0.010
c1	0.150	0.250	0.006	0.010
D1	4.900	5.100	0.193	0.201
D2	4.320	4.520	0.170	0.178
E	4.900	5.100	0.193	0.201
E1	5.900	6.100	0.232	0.240
E2	3.920	4.12	0.154	0.162
e	1.27 TYP		0.050	
K	0.760		0.030	
L	0.510	0.710	0.020	0.028
$\theta$	0.00			



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
F1	6.205	6.305	0.244	0.248
F2	4.460	4.560	0.176	0.180
F3	4.460	4.560	0.176	0.180
F4	0.650	0.700	0.026	0.028
F5	0.620	0.670	0.024	0.026
F6	0.630	0.680	0.025	0.027
F7	0.700	0.800	0.028	0.031
F8	0.650	0.700	0.026	0.028
F9	0.620	0.670	0.024	0.026
F10	4.900	5.000	0.193	0.197
F11	4.460	4.560	0.176	0.180

For recommended circuit layout for PCB designs, see application note [SLPA005](#) – *Reducing Ringing Through PCB Layout Techniques*.

## Q5 Tape and Reel Information



### Notes:

- 10-sprocket hole-pitch cumulative tolerance  $\pm 0.2$
- Camber not to exceed 1mm in 100mm, noncumulative over 250mm
- Material: black static-dissipative polystyrene
- All dimensions are in mm (unless otherwise specified)
- Thickness:  $0.30 \pm 0.05$ mm
- MSL1 260°C (IR and convection) PbF reflow compatible

REVISION HISTORY

Changes from Original (January 2010) to Revision A	Page
<ul style="list-style-type: none"><li>Changed the Abs Max Ratings table, Avalanche Energy, single pulse From: <math>I_D = 85A</math>, <math>L = 0.1mH</math>, <math>R_G = 25\Omega</math> Value = 361 To: <math>I_D = 103A</math>, <math>L = 0.1mH</math>, <math>R_G = 25\Omega</math> Value = 530 .....</li><li>Changed <a href="#">Figure 11</a> .....</li></ul>	<div>1</div> <div>5</div>
Changes from Revision A (February 2010) to Revision B	Page
<ul style="list-style-type: none"><li>Deleted the Package Marking Information section .....</li></ul>	<div>7</div>



## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD17303Q5	ACTIVE	VSON-CLIP	DQH	8	2500	Green (RoHS & no Sb/Br)	SN	Level-1-260C-UNLIM	-55 to 150	CSD17303	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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